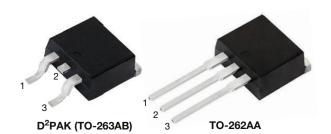
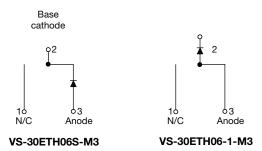


www.vishay.com

Vishay Semiconductors

Hyperfast Rectifier, 30 A FRED Pt®





| PRIMARY CHARACTERISTICS | | | | | | |
|----------------------------------|-----------------------------------------|--|--|--|--|--|
| I _{F(AV)} | 30 A | | | | | |
| V_R | 600 V | | | | | |
| V _F at I _F | 1.34 V | | | | | |
| t _{rr} typ. | 28 ns | | | | | |
| T _J max. | 175 °C | | | | | |
| Package | D ² PAK (TO-263AB), TO-262AA | | | | | |
| Circuit configuration | Single | | | | | |

FEATURES

- Hyperfast recovery time
- Low forward voltage drop
- Low leakage current
- 125 °C operating junction temperature



- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

| ABSOLUTE MAXIMUM RATINGS | | | | | | | |
|---------------------------------------------|-----------------------------------|-------------------------|-------------|-------|--|--|--|
| PARAMETER | SYMBOL | TEST CONDITIONS | MAX. | UNITS | | | |
| Peak repetitive reverse voltage | V_{RRM} | | 600 | V | | | |
| Average rectified forward current | I _{F(AV)} | T _C = 103 °C | 30 | ۸ | | | |
| Non-repetitive peak surge current | I _{FSM} | T _J = 25 °C | 200 | A | | | |
| Operating junction and storage temperatures | T _J , T _{Stg} | | -65 to +175 | °C | | | |

| ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified) | | | | | | | | |
|--------------------------------------------------------------------------------------|--------------------|--------------------------------------------------------|------|------|-------|----|--|--|
| PARAMETER | SYMBOL | MIN. | TYP. | MAX. | UNITS | | | |
| Breakdown voltage, blocking voltage | V_{BR} , V_{R} | Ι _R = 100 μΑ | 600 | - | - | ., | | |
| Famous de la ses | V_{F} | I _F = 30 A | - | 2.0 | 2.6 | V | | |
| Forward voltage | ٧F | I _F = 30 A, T _J = 150 °C | - | 1.34 | 1.75 | | | |
| Reverse leakage current | 1 | $V_R = V_R$ rated | - | 0.3 | 50 | | | |
| neverse leakage current | I _R | $T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$ | - | 60 | 500 | μA | | |
| Junction capacitance | C _T | $V_{R} = 600 \text{ V}$ | - | 33 | - | pF | | |
| Series inductance | L _S | Measured lead to lead 5 mm from package body | - | 8.0 | - | nΗ | | |

VS-30ETH06S-M3, VS-30ETH06-1-M3

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| DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified) | | | | | | | | |
|---------------------------------------------------------------------------------------------|------------------|-------------------------------------|----------------------------------------------------------------|------|------|------|-------|--|
| PARAMETER | SYMBOL | TEST CO | NDITIONS | MIN. | TYP. | MAX. | UNITS | |
| Reverse recovery time | | $I_F = 1.0 \text{ A}, dI_F/dt = 50$ |) A/μs, V _R = 30 V | - | 28 | 35 | | |
| | t _{rr} | T _J = 25 °C | | - | 31 | - | ns | |
| | | T _J = 125 °C | I _F = 30 A | - | 77 | =. | | |
| Dools week to a comment | | T _J = 25 °C | | - | 3.5 | =. | Α | |
| Peak recovery current | I _{RRM} | T _J = 125 °C | $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$ | - | 7.7 | =. | | |
| Reverse recovery charge | 0 | T _J = 25 °C | | - | 65 | - | ~C | |
| | Q_{rr} | T _J = 125 °C | | - | 345 | - | nC | |

| THERMAL - MECHANICAL SPECIFICATIONS | | | | | | | | |
|-------------------------------------------------|-----------------------------------|---------------------------------------------------|--------------|------|------------|------------------------|--|--|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS | | |
| Maximum junction and storage temperature range | T _J , T _{Stg} | | -65 | - | 175 | °C | | |
| Thermal resistance, junction to case per leg | R _{thJC} | | - | 0.7 | 1.1 | | | |
| Thermal resistance, junction to ambient per leg | R _{thJA} | Typical socket mount | - | - | 70 | °C/W | | |
| Thermal resistance, case to heatsink | R _{thCS} | Mounting surface, flat, smooth, and greased | - | 0.2 | - | | | |
| Weight | | | - | 2.0 | - | g | | |
| vveigni | | | - | 0.07 | - | oz. | | |
| Mounting torque | | | 6.0 (5.0) | - | 12 (10) | kgf · cm (lbf · in) | | |
| Madia da ia | | Case style D ² PAK (TO-263AB) 30ETH06S | | | H06S | | | |
| Marking device | | Case style TO-262AA | 30ETH06-1 | | | | | |

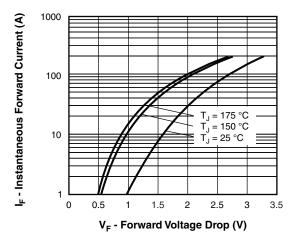


Fig. 1 - Typical Forward Voltage Drop Characteristics

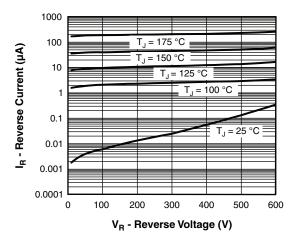


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

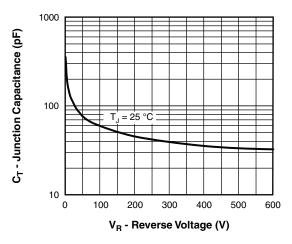


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

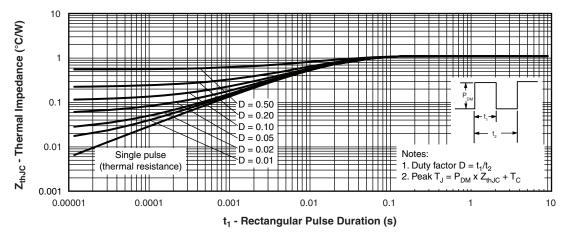


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

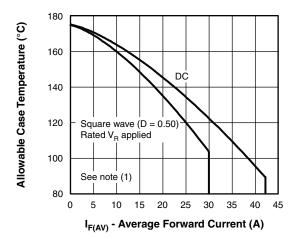


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

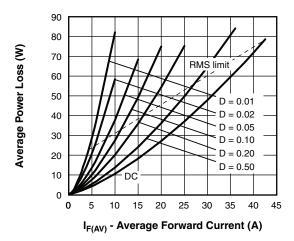


Fig. 6 - Forward Power Loss Characteristics

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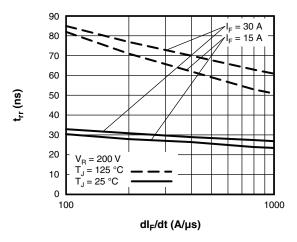


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

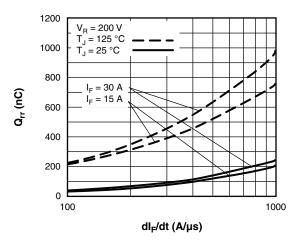
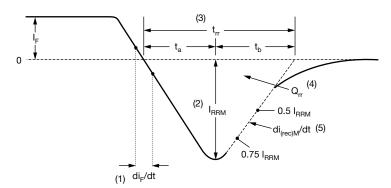


Fig. 8 - Typical Stored Charge vs. dl_F/dt

Note

 $^{(1)}$ Formula used: T_C = T_J - (Pd + Pd_{REV}) x R_{thJC}; Pd = forward power loss = I_{F(AV)} x V_{FM} at (I_{F(AV)}/D) (see fig. 6); Pd_{REV} = inverse power loss = V_{R1} x I_R (1 - D); I_R at V_{R1} = rated V_R



- di_F/dt rate of change of current through zero crossing
- (2) $\ensuremath{\mbox{I}_{\mbox{\footnotesize RRM}}}$ peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_{F}$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}

$$Q_{rr} = \frac{t_{rr} x I_{RRM}}{2}$$

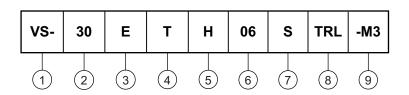
(5) di_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



Vishay Semiconductors product

2 - Current rating (30 = 30 A)

3 - E = single

T = TO-220, D²PAK (TO-263AB)

5 - H = hyperfast recovery

6 - Voltage rating (06 = 600 V)

- • S = D^2 PAK (TO-263AB)

• -1 = TO-26 2AA

None = tube (50 pieces)

• TRL = tape and reel (left oriented, for D²PAK (TO-263AB) package)

• TRR = tape and reel (right oriented, for D²PAK (TO-263AB) package)

9 - Environmental digit:

-M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

| ORDERING INFORMATION (Example) | | | | | | |
|--------------------------------|---------------|------------------------------------|--|--|--|--|
| PREFERRED P/N | BASE QUANTITY | PACKAGING DESCRIPTION | | | | |
| VS-30ETH06S-M3 | 50 | Antistatic plastic tubes | | | | |
| VS-30ETH06STRL-M3 | 800 | 13" diameter plastic tape and reel | | | | |
| VS-30ETH06STRR-M3 | 800 | 13" diameter plastic tape and reel | | | | |
| VS-30ETH06-1-M3 | 50 | Antistatic plastic tubes | | | | |

| LINKS TO RELATED DOCUMENTS | | | | | | |
|----------------------------|-------------------------------|--------------------------|--|--|--|--|
| Dimensions | D ² PAK (TO-263AB) | www.vishay.com/doc?96164 | | | | |
| Dimensions | TO-262AA | www.vishay.com/doc?96165 | | | | |
| Part marking information | D ² PAK (TO-263AB) | www.vishay.com/doc?95444 | | | | |
| | TO-262AA | www.vishay.com/doc?95443 | | | | |
| Packaging information | | www.vishay.com/doc?96424 | | | | |



D²PAK

DIMENSIONS in millimeters and inches



| SYMBOL | MILLIM | ETERS | INC | HES | NOTES | SYMBOL | MILLIM | ETERS | INC | HES | NOTES |
|----------|--------|-------|-------|-------|-------|----------|--------|-------|-------|-------|-------|
| STIVIBUL | MIN. | MAX. | MIN. | MAX. | NOIES | STINIBUL | MIN. | MAX. | MIN. | MAX. | NOTES |
| Α | 4.06 | 4.83 | 0.160 | 0.190 | | D1 | 6.86 | 8.00 | 0.270 | 0.315 | 3 |
| A1 | 0.00 | 0.254 | 0.000 | 0.010 | | E | 9.65 | 10.67 | 0.380 | 0.420 | 2, 3 |
| b | 0.51 | 0.99 | 0.020 | 0.039 | | E1 | 7.90 | 8.80 | 0.311 | 0.346 | 3 |
| b1 | 0.51 | 0.89 | 0.020 | 0.035 | 4 | е | 2.54 | BSC | 0.100 | BSC | |
| b2 | 1.14 | 1.78 | 0.045 | 0.070 | | Н | 14.61 | 15.88 | 0.575 | 0.625 | |
| b3 | 1.14 | 1.73 | 0.045 | 0.068 | 4 | L | 1.78 | 2.79 | 0.070 | 0.110 | |
| С | 0.38 | 0.74 | 0.015 | 0.029 | | L1 | - | 1.65 | - | 0.066 | 3 |
| c1 | 0.38 | 0.58 | 0.015 | 0.023 | 4 | L2 | 1.27 | 1.78 | 0.050 | 0.070 | |
| c2 | 1.14 | 1.65 | 0.045 | 0.065 | | L3 | 0.25 | BSC | 0.010 | BSC | |
| D | 8.51 | 9.65 | 0.335 | 0.380 | 2 | L4 | 4.78 | 5.28 | 0.188 | 0.208 | |

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inches
- (7) Outline conforms to JEDEC® outline TO-263AB

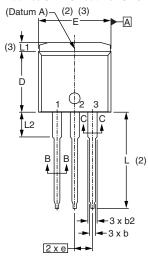
Revision: 13-Jul-17 Document Number: 96164

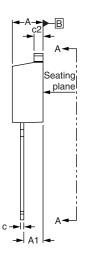


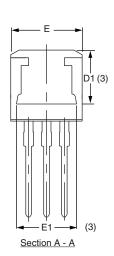
TO-262AA

DIMENSIONS in millimeters and inches

Modified JEDEC® outline TO-262







⊕ 0.010 **M** A**M** B

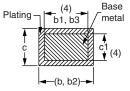
Lead assignments



Diodes 1. - Anode (two die)/open (one die)

2., 4. - Cathode

3. - Anode



Section B - B and C - C Scale: None

| SYMBOL | MILLIM | IETERS | INC | INCHES | | | |
|--------|--------|----------|-------|--------|-------|--|--|
| | MIN. | MAX. | MIN. | MAX. | NOTES | | |
| Α | 4.06 | 4.83 | 0.160 | 0.190 | | | |
| A1 | 2.03 | 3.02 | 0.080 | 0.119 | | | |
| b | 0.51 | 0.99 | 0.020 | 0.039 | | | |
| b1 | 0.51 | 0.89 | 0.020 | 0.035 | 4 | | |
| b2 | 1.14 | 1.78 | 0.045 | 0.070 | | | |
| b3 | 1.14 | 1.73 | 0.045 | 0.068 | 4 | | |
| С | 0.38 | 0.74 | 0.015 | 0.029 | | | |
| c1 | 0.38 | 0.58 | 0.015 | 0.023 | 4 | | |
| c2 | 1.14 | 1.65 | 0.045 | 0.065 | | | |
| D | 8.51 | 9.65 | 0.335 | 0.380 | 2 | | |
| D1 | 6.86 | 8.00 | 0.270 | 0.315 | 3 | | |
| Е | 9.65 | 10.67 | 0.380 | 0.420 | 2, 3 | | |
| E1 | 7.90 | 8.80 | 0.311 | 0.346 | 3 | | |
| е | 2.54 | 2.54 BSC | | 0 BSC | | | |
| L | 13.46 | 14.10 | 0.530 | 0.555 | | | |
| L1 | - | 1.65 | - | 0.065 | 3 | | |
| L2 | 3.56 | 3.71 | 0.140 | 0.146 | | | |

Notes

(4) Dimension b1 and c1 apply to base metal only

Controlling dimension: inches

⁽¹⁾ Dimensioning and tolerancing as per ASME Y14.5M-1994
(2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body

Thermal pad contour optional within dimension E, L1, D1 and E1

Outline conform to JEDEC® TO-262 except A1 (max.), b (min., max.), b1 (min.), b2 (max.), c (min.), c1(min.), c2 (max.), D (min.), E (max.), L1 (max.), L2 (min., max.)



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